

INTERNATIONAL DIRECTORY OF WAFER-BUMPING SERVICE PROVIDERS

Notes: This list was compiled from data supplied by the respective providers and is not all-inclusive as to company or service offered. Advertisers in this issue are indicated by **boldface** listings. CM=Consult Manufacturer.

Company Name Address ☎ Phone ✉ Fax 🏠 Year Founded	†† Number of Employees ✖ Maximum Wafer Size (mm) Ⓑ Bump Pitches (microns)	★ Equipment A=Aligners, B=Stencil Printers, C=Steppers ⓘ Bumping Technologies	[web site] ✨ Contact 🌐 Additional Offices 📄 Description of Services (advertisers only)
Aguila Technologies Inc. 310 Via Vera Cruz, Ste. 107 San Marcos, CA 92078 ☎ 760.725.1192 🏠 1996	†† 10 ✖ 200 Ⓑ 120 and up	★ A, B ⓘ Electroplating, screen printing	[aguilatech.com] ✨ M. Albert Capote, President macapote@aguilatech.com
ASE Group Kaohsiung, Taiwan 811 ☎ +886.7.361.3094 🏠 1984	†† 30,000+ ✖ 300 Ⓑ 150	★ A, C ⓘ Electroplating, screen printing	[aseglobal.com] ✨ Jennifer Yuen, Director of Marketing and Communications marketing@aseus.com 🌐 ASE U.S. Inc. Santa Clara, CA 95054 ☎ 408.986.6500
Chipbond Technology Corp. Hsinchu, Taiwan ☎ +886.567.8788 🏠 1997	†† 1,200 ✖ 200 Ⓑ 32 (Au), 100 (with height limitation)	★ A, C ⓘ Electroplating, ball placement	[chipbond.com.tw] ✨ Robert Hsu, VP of Sales and Marketing
FlipChip International Div. of Rose Street Labs 3701 E. University Dr. Phoenix, AZ 85034 ☎ 602.431.6020 ✉ 602.431.6021 🏠 1996	†† >200 ✖ 200 Ⓑ 70 (R&D), 150+ (in production)	★ A, C ⓘ Sputtered UBM, electroless Ni/Au UBM, solder paste, sphere drop solder alloys	[flipchip.com] ✨ Jay Hayes, Director of International Sales jay.hayes@flipchip.com ☎ 719.481.6444 📄 Flip chip and wafer bumping, Ultra CSP, EliteCSP, thinning, plus backend to T&R or chip trays
FuPo Electronics Corp. Hsinchu, Taiwan ☎ +886.3.5799339 🏠 1996	†† CM ✖ 200 Ⓑ 40	★ C ⓘ Electroplating	[fupo.com.tw] ✨ H.S. Wen, Sales & Marketing Director hs_wen@fupo.com.tw
IC Interconnect Div. of Eagle Electronics 1025 Elkton Dr. Colorado Springs, CO 80907 ☎ 719.533.1030 🏠 1998	†† 20 ✖ 200 (production), 300 (prototype) Ⓑ 200+ (design dependent)	★ B ⓘ Electroless Ni, immersion Au, UBM plating, solder deposition of wet paste or solid diameter spheres and reflow	[icinterconnect.com] ✨ Tony Gaines, Regional Sales Manager tgaines@icinterconnect.com
Pac Tech Packaging Technologies GmbH Am Schlangenhorst 15-17 14641 Nauen, Germany ☎ +49.3321.4995.0 ✉ +49.3321.4495.23 🏠 1995	†† 100 ✖ 300 Ⓑ 120 (solder) 40 (Ni/Au)	★ A, B ⓘ Electroless Ni/Au UBM, stencil printing, solder ball gang placement, solder jetting	[pactech.de] ✨ Thomas Oppert, VP Sales & Marketing sales@pactech.de 🌐 Pac Tech USA, 328 Martin Ave., Santa Clara, CA 95050 ✨ Dr. Thorsten Teutch, President and CTO sales@pactech-usa.com 📄 Low cost wafer-bumping service for mass production and prototyping in the U.S. and Europe.

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Siliconware Precision Industries Co. Ltd. Taichung, Taiwan ☎ +886.4.25341525 🏠 1984	†† 10,000 ✖ 300 Ⓑ 200/180/150/120 (area array), 150/100/80/60 (peripheral)	★ A, B, C ① Printing bump, plating bump	[spil.com.tw] 🌐 Siliconware USA Inc. 1735 Technology Dr., San Jose, CA 95110 ☎ 408.573.5500
STATS ChipPAC Ltd. Singapore 569059 ☎ +65.6824.7777 🏠 1995	†† 10,600 ✖ 300 Ⓑ 220, 200 (in production), 180, 150 (qualified)	★ A, B, C ① Electroplating for 300mm wafers and printing for 200mm wafers	[statschippac.com] 🌐 STATS ChipPAC Inc. 47400 Kato Rd., Fremont, CA 94538 ☎ 510.979.8000
Unitive Electronics Div. of Amkor Technology 140 Southcenter Ct. Morrisville, NC 27560 ☎ 919.941.0606 🏠 1997	†† CM ✖ 300 (Taiwan), 200 (U.S.) Ⓑ CM	★ A ① Ball loading, electroplating	[unitive.com] ✨ David Hays, VP Strategic Marketing & Business Development dhays@amkor.com